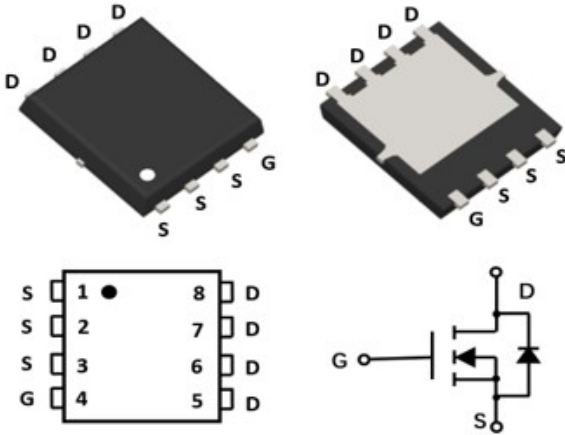


## N-Channel Enhancement Mode Field Effect Transistor

### PDFN 5X6



### Product Summary

- $V_{DS}$  40V
- $I_D$  90A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ ) < 4.5mohm
- $R_{DS(ON)}$  (at  $V_{GS}=4.5V$ ) < 6.5mohm
- 100% UIS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$

### Applications

- High current load applications
- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

### ■ Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	$V_{DS}$	40	V
Gate-source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current	$I_D$	$T_C=25^\circ\text{C}$	90
		$T_C=100^\circ\text{C}$	63
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	340	A
Total Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$	55
		$T_C=100^\circ\text{C}$	27.5
Single Pulse Avalanche Energy <sup>B</sup>	$E_{AS}$	220	mJ
Thermal Resistance Junction-to-Case <sup>C</sup>	$R_{\theta JC}$	2.73	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+175	$^\circ\text{C}$

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG90N04A	F1	YJG90N04A	5000	10000	100000	13" reel



# YJG90N04A

## ■ Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	40			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V			1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	0.7	1.2	2.0	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> =20A		3.5	4.5	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> =20A		4.4	6.5	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =20A, V <sub>GS</sub> =0V		0.85	1.2	V
Maximum Body-Diode Continuous Current	I <sub>S</sub>				90	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1MHZ		3440		pF
Output Capacitance	C <sub>oss</sub>			413		
Reverse Transfer Capacitance	C <sub>rss</sub>			314		
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =20, I <sub>D</sub> =20A		10.9		nC
Gate-Source Charge	Q <sub>gs</sub>			19.7		
Gate-Drain Charge	Q <sub>gd</sub>			89		
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =20A, di/dt=100A/us		7.3		ns
Reverse Recovery Time	t <sub>rr</sub>			24		
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =10V, V <sub>DD</sub> =20V, I <sub>D</sub> =2A, R <sub>L</sub> =1Ω R <sub>GEN</sub> =3Ω		9		ns
Turn-on Rise Time	t <sub>r</sub>			20		
Turn-off Delay Time	t <sub>D(off)</sub>			69		
Turn-off fall Time	t <sub>f</sub>			41		

A. Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

B. R<sub>θJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>θJC</sub> is guaranteed by design, while R<sub>θJA</sub> is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.



## ■ Typical Performance Characteristics

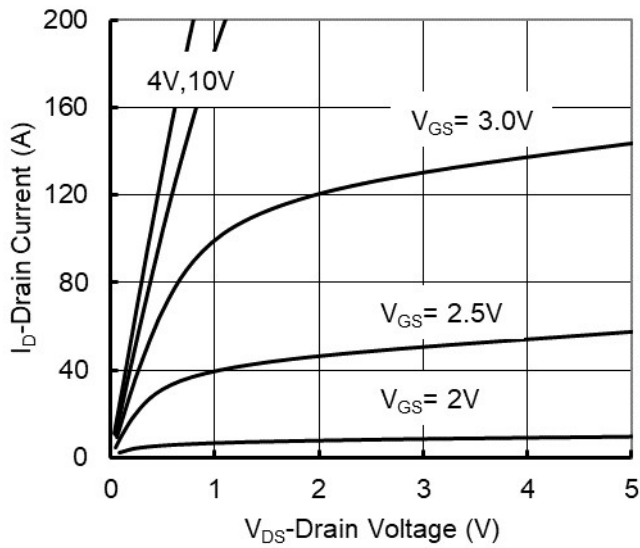


Figure 1. Output Characteristics

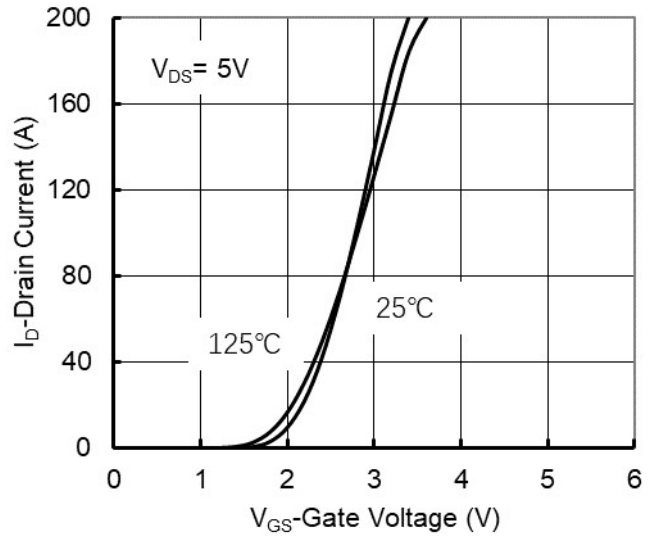


Figure 2. Transfer Characteristics

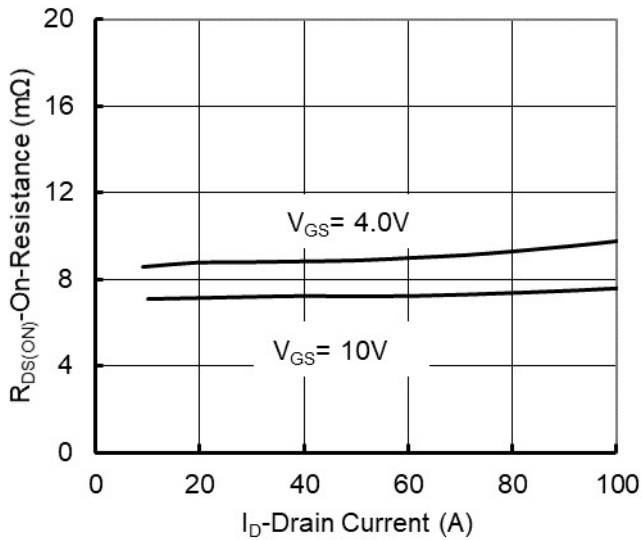


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

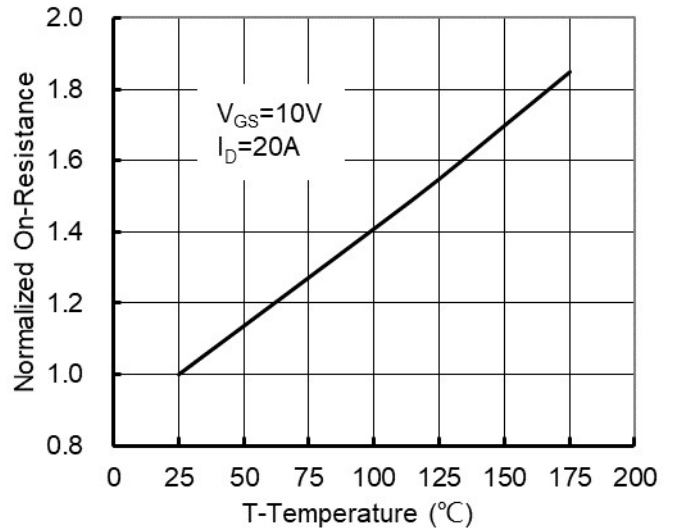


Figure 4. On-Resistance vs. Junction Temperature

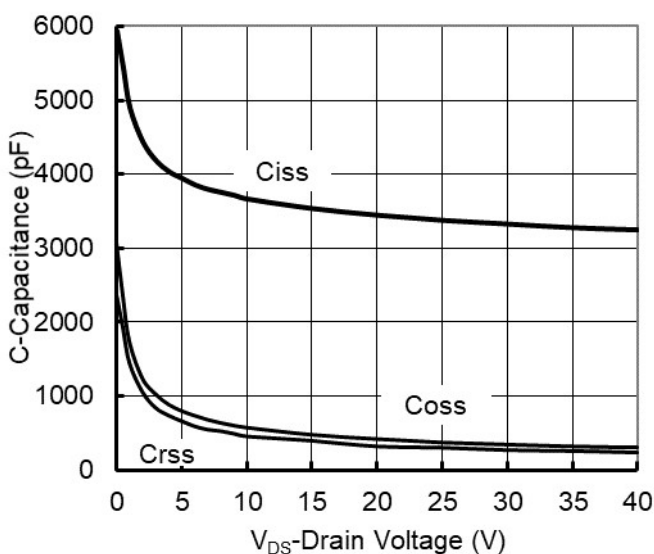


Figure 5. Capacitance Characteristics

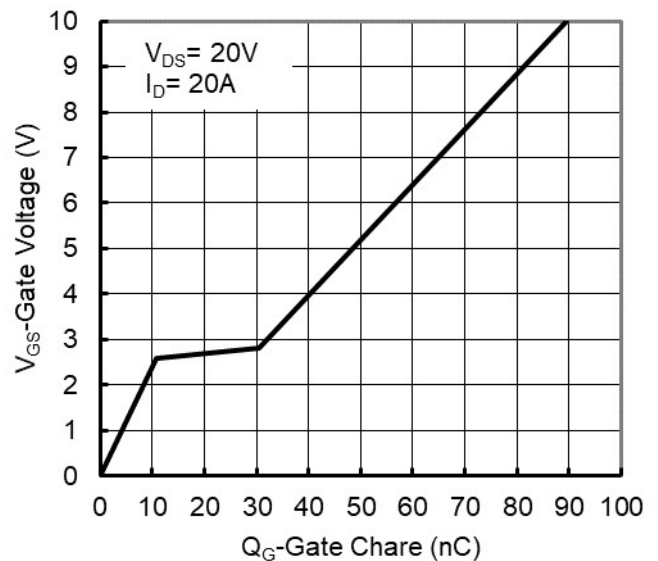


Figure 6. Gate Charge

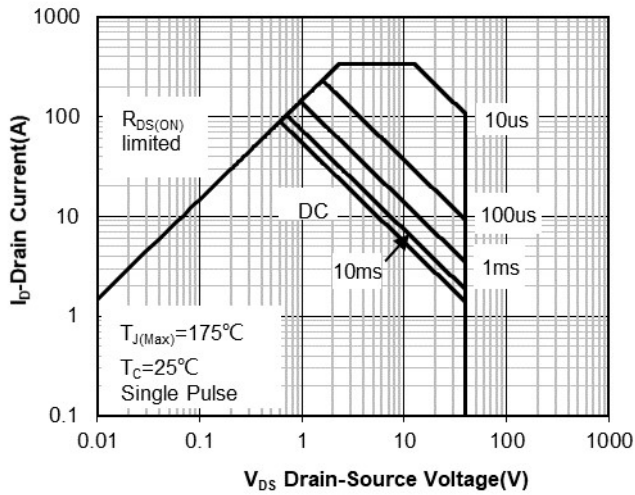


Figure 7. Safe Operation Area

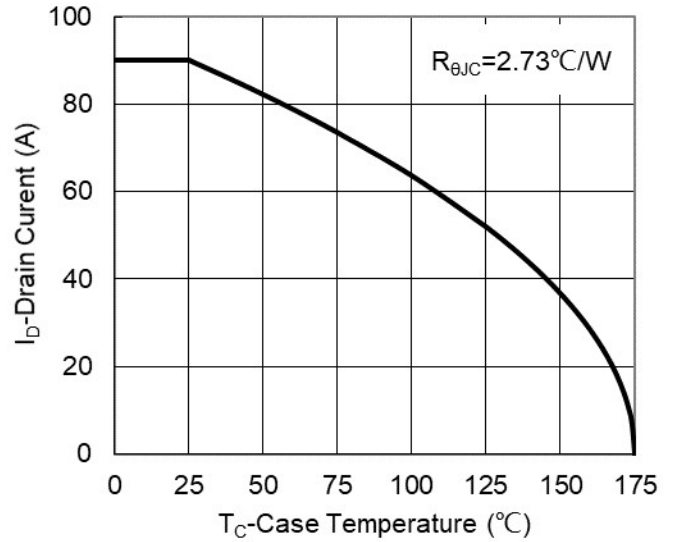


Figure 8. Maximum Continuous Drain Current vs Case Temperature

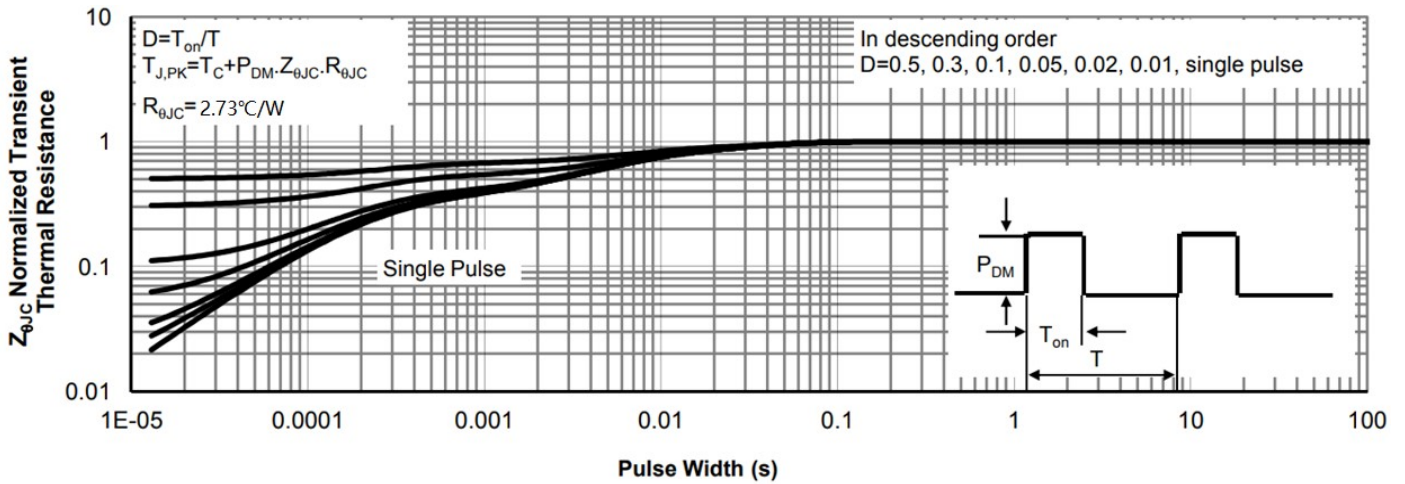


Figure 9. Normalized Maximum Transient Thermal Impedance



**Resistive Switching Test Circuit & Waveforms**



**Diode Recovery Test Circuit & Waveforms**



**Gate Charge Test Circuit & Waveform**

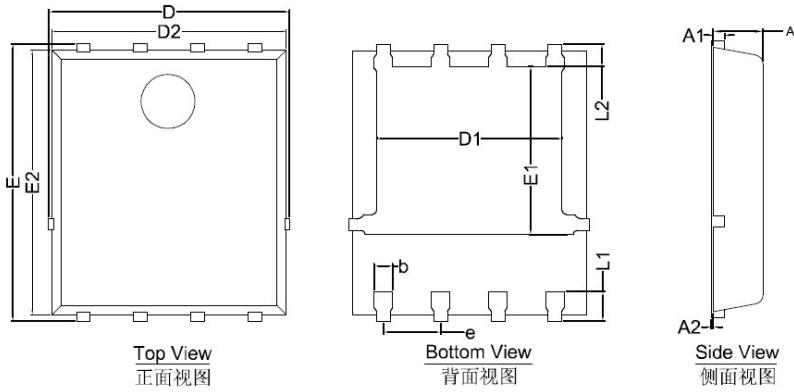


**Unclamped Inductive Switching (UIS) Test Circuit & Waveforms**

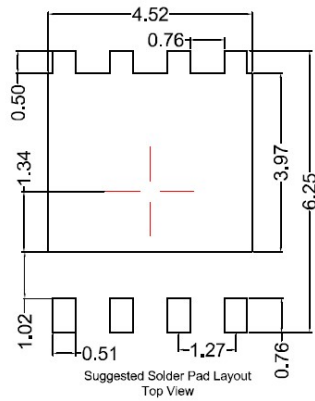


# YJG90N04A

## ■ PDFN5X6 Package information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1	0.254 BSC		
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
L1	0.56	0.66	0.76
L2	0.50 BSC		
b	0.31	0.41	0.51
e	1.27 BSC		



Note:  
 1. Controlling dimension: in millimeters.  
 2. General tolerance:  $\pm 0.10$ mm.  
 3. The pad layout is for reference purposes only.



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